

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

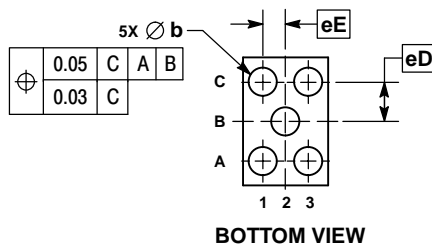
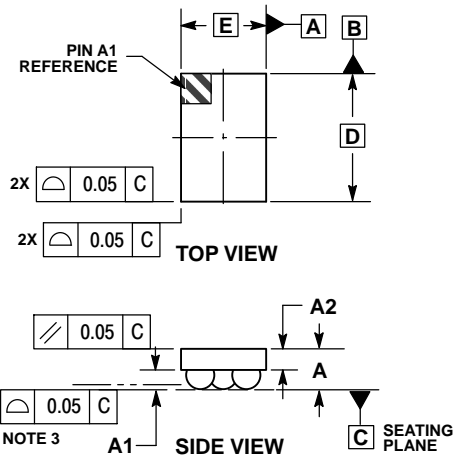
ON Semiconductor®



SCALE 4:1

WLCSP5, 1.41x0.94
CASE 567LT
ISSUE O

DATE 05 JUN 2015



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.40	0.50
A1	0.21	0.27
A2	0.23 REF	
b	0.29	0.35
D	1.41 BSC	
E	0.94 BSC	
eD	0.435 BSC	
eE	0.25 BSC	

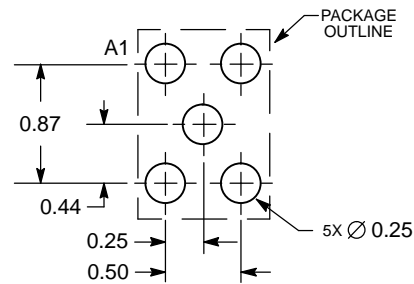
GENERIC MARKING DIAGRAM*



- X = Specific Device Code
- M = Month Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	WLCSP5, 1.41X0.94	PAGE 1 OF 2

